

R8006KNX

Nch 800V 6A Power MOSFET

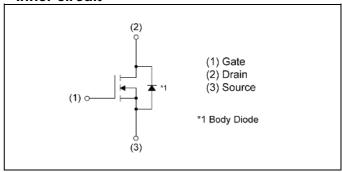
V _{DSS}	800V
R _{DS(on)} (Max.)	0.90Ω
I _D	±6A
P _D	52W

● Package TO-220FM (1)(2)(3)

Features

- 1) Low on-resistance
- 2) Fast switching
- 3) Parallel use is easy
- 4) Pb-free plating ; RoHS compliant

•Inner circuit



Application

Switching applications

Marking specification

Marking	R8006KNX
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● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		V_{DSS}	800	V
Continuous drain current		I _D *1	±6	Α
Pulsed drain current		I _{DP} *2	±18	Α
Coto Course valters	Static	V	±20	V
Gate - Source voltage	AC (f>1Hz)	V_{GSS}	±30	V
Avalanche current, single pulse		I _{AS}	1.2	А
Avalanche energy, single pulse		E _{AS} *3	76	mJ
Power dissipation (T _c = 25°C)	P _D	52	W	
Junction temperature	T _j	150	°C	
Operating junction and storage tempe	rature range	T _{stg}	-55 to +150	°C

Thermal characteristics

Dougrantou	Currely el	Values			1.1:4
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R _{th(j-c)} *4	-	-	2.4	°C/W
Thermal resistance, junction - ambient	R _{th(j-a)}	-	-	75	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	°C

● Static characteristics (T_a = 25°C)

Daramatar	Cumb al	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 1mA	800	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} = 800V, V _{GS} = 0V	1	1	100	μA
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 20V$, $V_{DS} = 0V$	1	1	±100	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 4mA$	2.5	3.5	4.5	٧
Static drain - source on - state resistance	R _{DS(on)} *5	V _{GS} = 10V, I _D = 3A	-	0.75	0.90	Ω

● Dynamic characteristics (T_a = 25°C)

Darramatar	Cymah al	Conditions	Values			Linit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Gate resistance	R_{G}	f = 1MHz, open drain	-	3	-	Ω
Input capacitance	C _{iss}	V _{GS} = 0V, VDS = 100V	-	650	-	
Output capacitance	C _{oss}	f = 1MHz	-	45	-	
Effective output capacitance energy related	C _{o(er)} *6	V _{GS} = 0V	-	9	-	pF
Effective output capacitance time related	C _{o(tr)} *7	V _{DS} = 0V to 400V	-	41	-	
Turn - on delay time	t _{d(on)} *5	V _{DD} ≈ 400V, V _{GS} = 10V	-	15	-	
Rise time	t _r *5	I _D = 3A	-	30	-	20
Turn - off delay time	t _{d(off)} *5	R _L ≃ 133Ω	-	40	-	ns
Fall time	t _f *5	$R_G = 10\Omega$	-	45	-	

● Gate charge characteristics (T_a = 25°C)

Darameter	Cumb al	Conditions	Values			Unit
Parameter	Symbol Conditions		Min.	Тур.	Max.	Offic
Total gate charge	Q_g^{*5}	V _{DD} ≃ 400V	-	22	1	
Gate - Source charge	Q _{gs} *5	I _D = 6A	-	3	1	nC
Gate - Drain charge	Q _{gd} *5	V _{GS} = 10V	-	9	1	
Gate plateau voltage	V _(plateau)	V _{DD} ≈ 400V, I _D = 6A	-	4.0	-	V

● Body diode characteristics (Source-Drain) (T_a = 25°C)

Daramatar	Cymahal	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	UIIIL	
Source current	I _S *1	· T _C = 25°C	-	-	6	А	
Pulsed source current	l _{SP} *2	1C - 25 C	-	-	18	Α	
Source-Drain voltage	V _{SD} *5	$V_{GS} = 0V$, $I_S = 6A$	-	-	1.5	V	
Reverse recovery time	t _{rr} *5		-	400	-	ns	
Reverse recovery charge	Q_{rr}^{*5}	I _S = 6A di/dt = 100A/μs	-	5.0	-	μC	
Peak reverse recovery current	_{rr} *5		-	25	-	Α	

^{*1} Limited only by maximum channel temperature allowed

^{*2} Pw ≤ 10µs, Duty cycle ≤ 1%

^{*3} L $\stackrel{.}{=}$ 100mH, V_{DD}=50V, R_G=25 Ω , STARTING T_j=25 $^{\circ}$ C

^{*4} T_C=25°C

^{*5} Pulsed

 $^{^{*}}$ 6 Co(er) is a fixed capacitance that gives the same stored energy as Coss while V_{DS} is rising from 0 to 50% V_{DSS}

^{*7} Co(er) is a fixed capacitance that gives the same charging time as Coss while V_{DS} is rising from 0 to 50% V_{DSS}

Fig.1 Power Dissipation Derating Curve

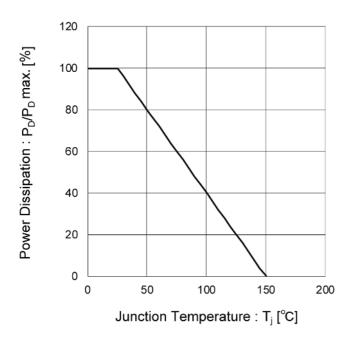


Fig.2 Drain Current Derating Curve

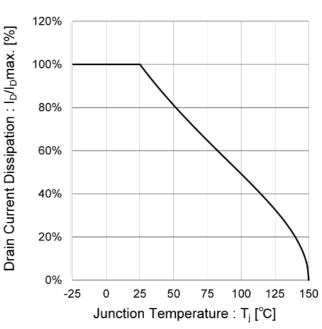


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

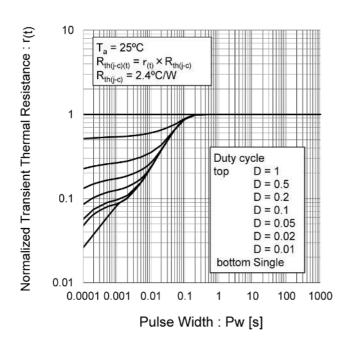
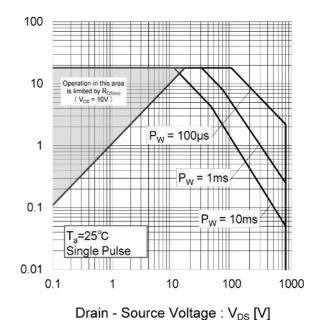


Fig.4 Maximum Safe Operating Area



Drain Current : I_D [A]

Fig.5 Avalanche Energy Derating Curve

120 Avalanche Energy: EAS / EAS max [%] 100 80 60 40 20 0 0 25 50 75 100 125 150 175 Junction Temperature : T_j [°C]

Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

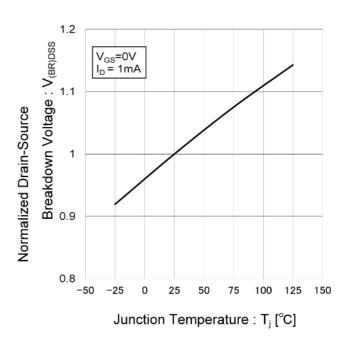


Fig.7 Output Characteristics(I))

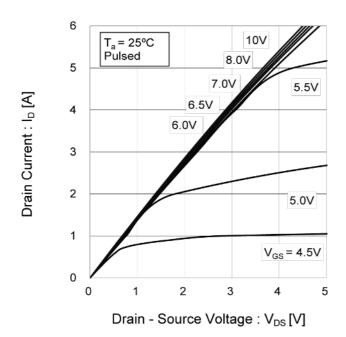
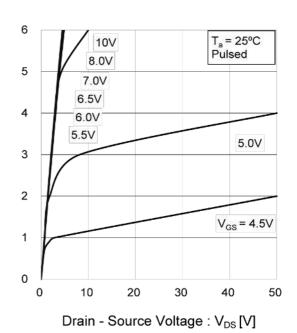


Fig.8 Output Characteristics(II)



Drain Current: Ip [A]

Fig.9 Gate Threshold Voltage vs. Drain Current

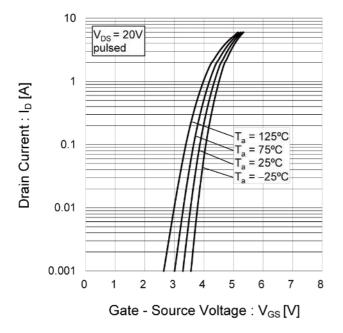


Fig.10 Normalized Gate Threshold

Voltage vs. Junction Temperature

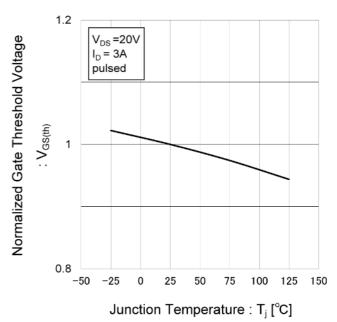


Fig.11 Static Drain - Source On - State Resistance vs. Drain Current

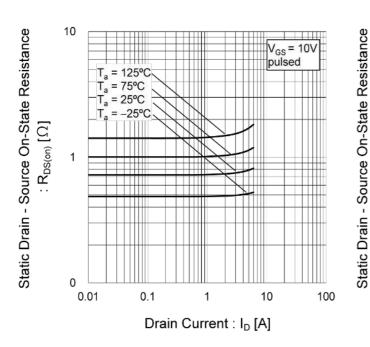


Fig.12 Static Drain - Source On - State Resistance vs. Gate - Source Voltage

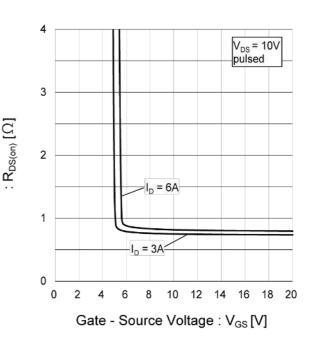


Fig.13 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature

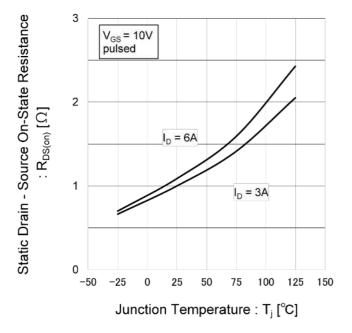


Fig.14 Capacitances

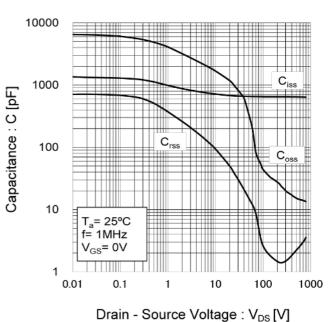


Fig.15 Switching Times

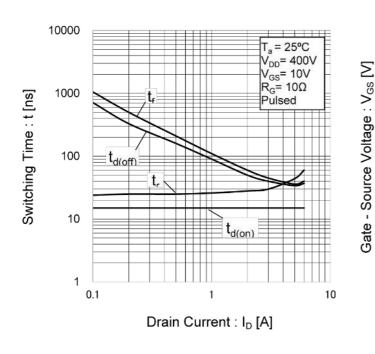


Fig.16 Gate Charge

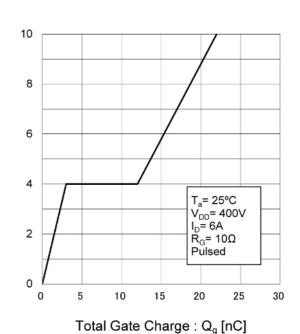
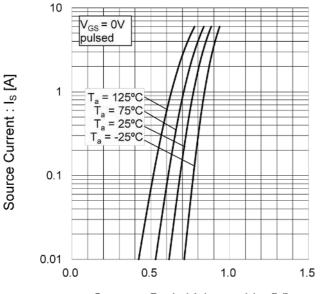
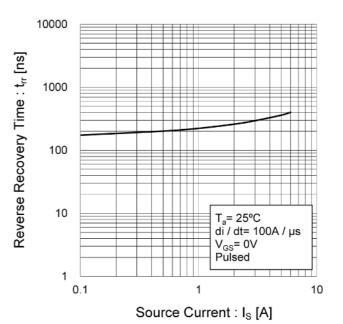


Fig.17 Source Current vs. Source - Drain Voltage



Source - Drain Voltage : V_{SD} [V]

Fig.18 Reverse Recovery Time vs. Source Current



Measurement circuits

Fig.1-1 Switching time measurement circuit

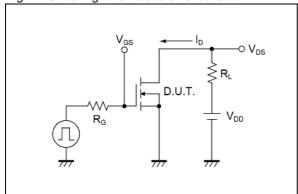


Fig.2-1 Gate charge measurement circuit

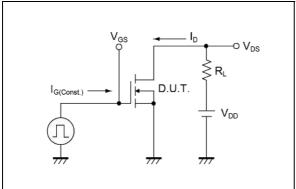


Fig.3-1 Avalanche measurement circuit

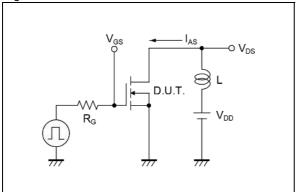


Fig.4-1 trr measurement circuit

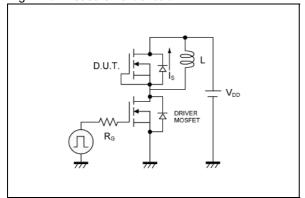


Fig.1-2 Switching waveforms

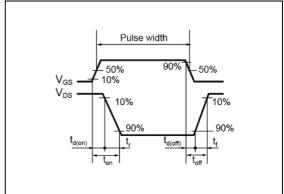


Fig.2-2 Gate charge waveform

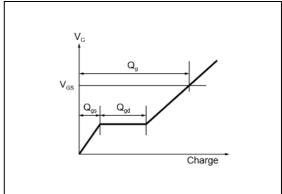


Fig.3-2 Avalanche waveform

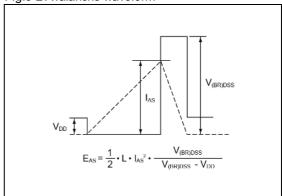
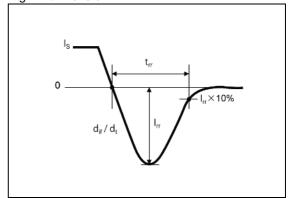
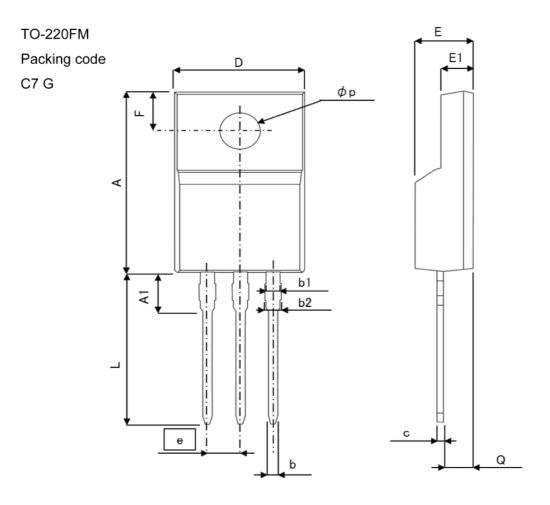


Fig.4-2 trr waveform



Dimensions



DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	15.67	16.27	0.617	0.641
A1	3.03	3.43	0.119	0.135
b	0.70	0.95	0.028	0.037
b1	1.00	1.40	0.039	0.055
b2	1.10	1.50	0.043	0.059
С	0.45	0.65	0.018	0.026
D	9.90	10.30	0.390	0.406
E	4.60	5.00	0.181	0.197
E1	2.44	2.74	0.096	0.108
е	2.	54	0.1	00
F	3.10	3.50	0.122	0.138
L	12.6	13.6	0.946	0.535
р	2.98	3.38	0.117	0.133
Q	2.25	3.25	0.089	0.128

Dimension in mm/inches



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JAPAN	USA	EU	CHINA
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CLASSIV	CLASSII	CLASSⅢ	CLASSⅢ

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 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
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- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
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- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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